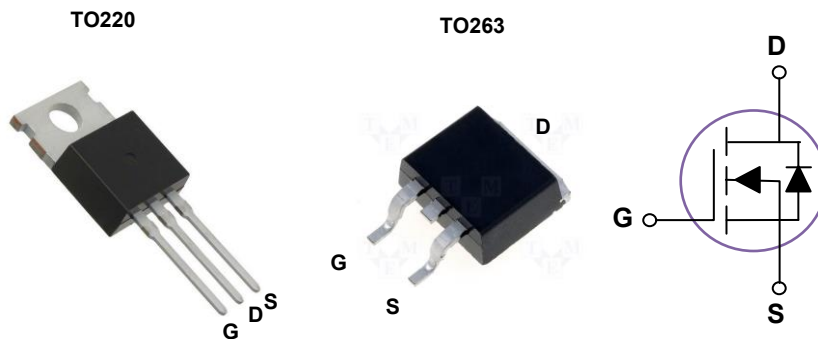


General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

Features

V_{DS}	80V
I_D (at $V_{GS}=10V$)	140A
$R_{DS(ON)}$ (at $V_{GS}=10V$)	3.7m Ω (Typ)



Absolute Maximum Ratings $T_A=25^\circ C$ unless otherwise noted

Parameter	Symbol	Maximum	Units	
Drain-Source Voltage	V_{DS}	80	V	
Gate-Source Voltage	V_{GS}	+20/-12	V	
Drain Current-Continuous	TC=25°C	I_D	140	A
	TC=100°C	I_D	89	A
Maximum Power Dissipation	P_D	150	W	
Single pulse avalanche energy ⁽¹⁾	E_{AS}	540	mJ	
Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 150	°C	

Thermal Characteristics

Parameter	Symbol	Typ	Max	Unit
Thermal Resistance junction-case	$R_{\theta Jc}$		1.1	°C /W
Thermal Resistance unction-to-Ambient	$R_{\theta JA}$		62	°C /W

Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Condition	Min	Typ	Max	Unit
STATIC PARAMETERS						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	80			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =80V, V _{GS} =0V			1	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =20V, V _{DS} =0V			100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	2.0	3.0	4.0	V
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =10V, I _D =20A		3.7	4.4	mΩ
DYNAMIC PARAMETERS						
C _{ISS}	Input Capacitance	V _{DS} =30V, V _{GS} =0V, F=1.0MHz		5500		pF
C _{OSS}	Output Capacitance			970		pF
C _{RSS}	Reverse Transfer Capacitance			35		pF
SWITCHING PARAMETERS						
t _{d(on)}	Turn-on Delay Time	V _{DD} =40V, I _D =1A, V _{GS} =10V, R _G =6Ω		22		nS
t _r	Turn-on Rise Time			16		nS
t _{d(off)}	Turn-Off Delay Time			40		nS
t _f	Turn-Off Fall Time			19		nS
Q _g	Total Gate Charge	V _{DS} =40V, I _D =10A, V _{GS} =10V		95		nC
Q _{gs}	Gate-Source Charge			23		nC
Q _{gd}	Gate-Drain Charge			32		nC
V _{SD}	Diode Forward Voltage	V _{GS} =0V, I _{SD} =10A		0.72	1.2	V
R _g	Gate resistance	V _{GS} =0V, V _{DS} =0V, F=1MHz		1.5		Ω

Note:

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=95A., Starting T_J=25°C
3. The data tested by pulsed , pulse width ≅ 300us , duty cycle ≅ 2%.
4. Essentially independent of operating temperature.

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

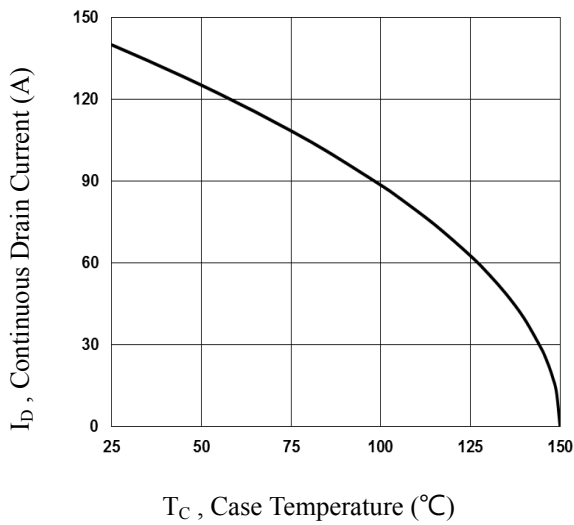


Fig.1 Continuous Drain Current vs. T_C

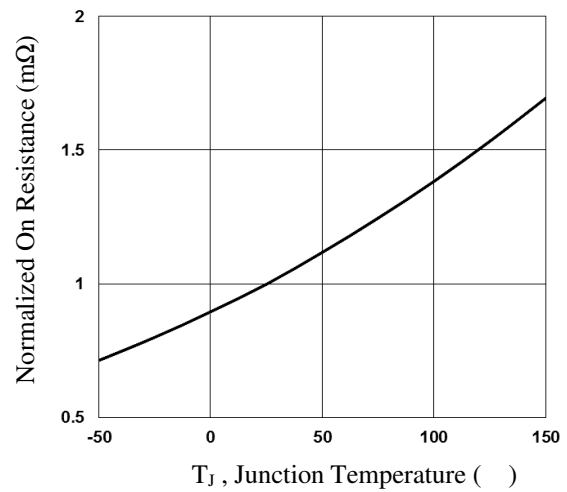


Fig.2 Normalized $R_{DS(on)}$ vs. T_J

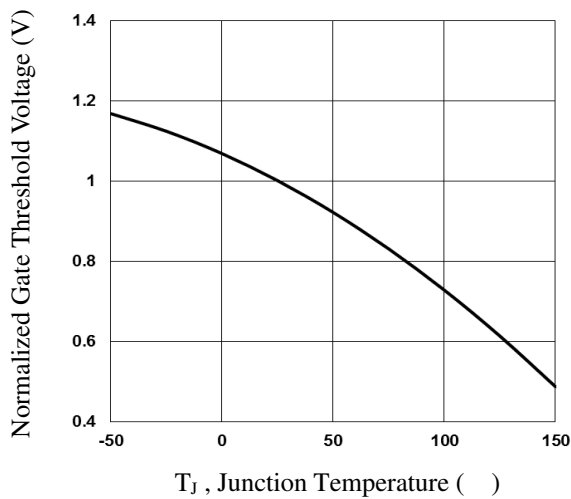


Fig.3 Normalized V_{th} vs. T_J

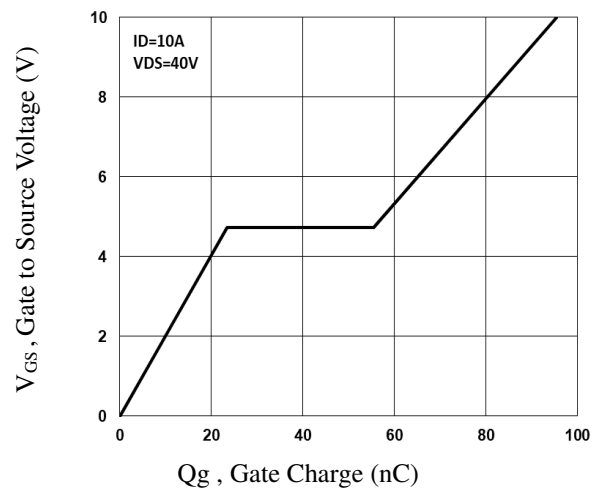


Fig.4 Gate Charge Characteristics

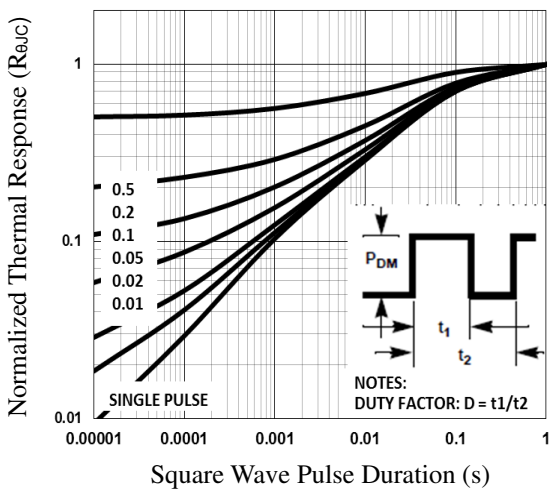


Fig.5 Normalized Transient Impedance

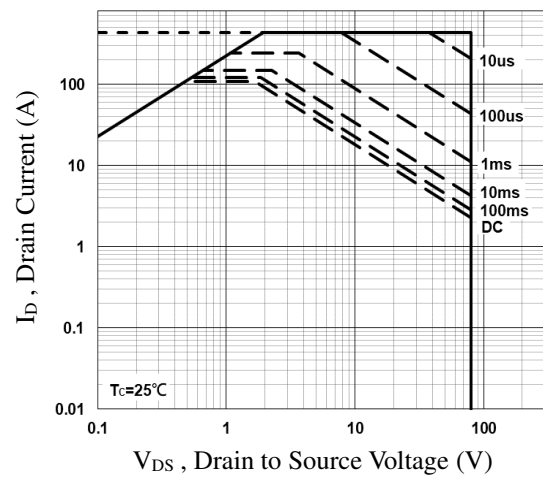


Fig.6 Maximum Safe Operation Area

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

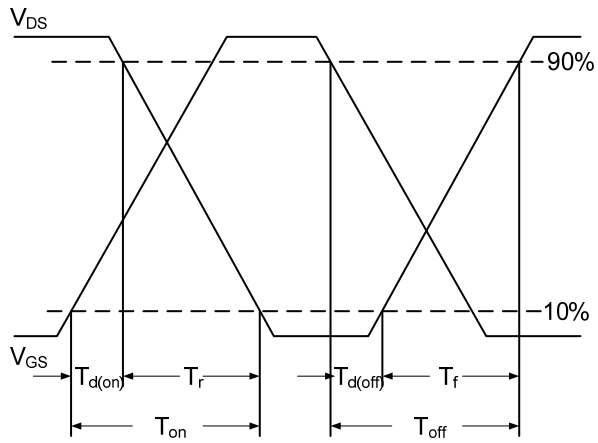


Fig.7 Switching Time Waveform

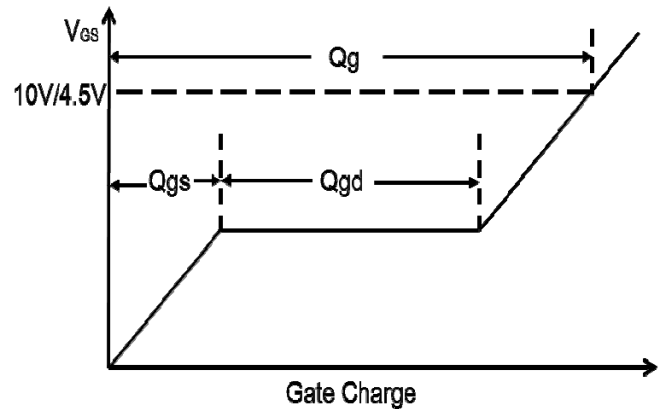
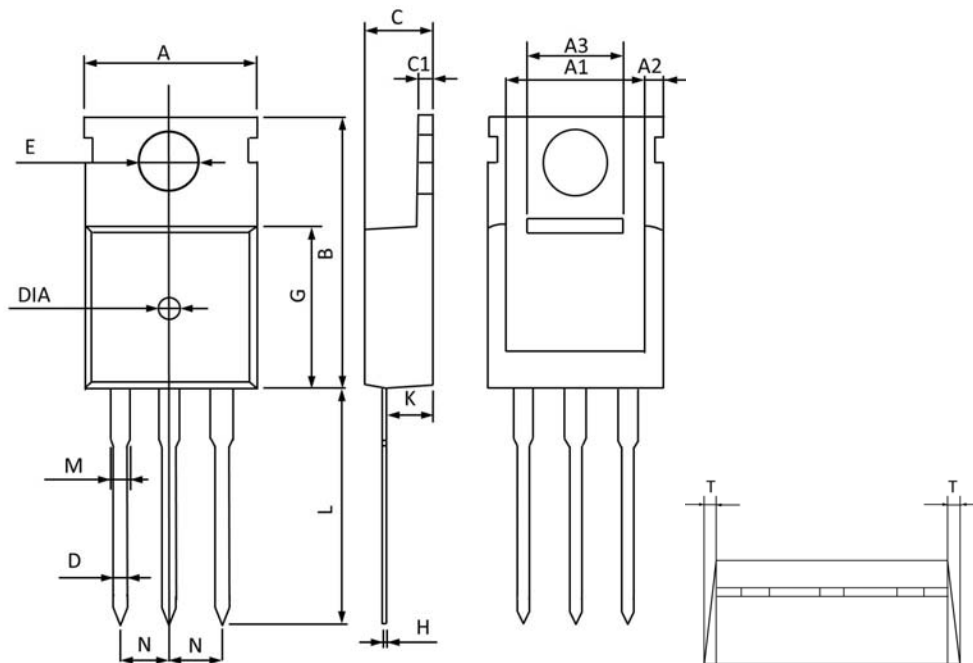


Fig.8 Gate Charge Waveform

TO220 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	10.300	9.700	0.406	0.382
A1	8.840	8.440	0.348	0.332
A2	1.250	1.050	0.049	0.041
A3	5.300	5.100	0.209	0.201
B	16.200	15.400	0.638	0.606
C	4.680	4.280	0.184	0.169
C1	1.500	1.100	0.059	0.043
D	1.000	0.600	0.039	0.024
E	3.800	3.400	0.150	0.134
G	9.300	8.700	0.366	0.343
H	0.600	0.400	0.024	0.016
K	2.700	2.100	0.106	0.083
L	13.600	12.800	0.535	0.504
M	1.500	1.100	0.059	0.043
N	2.590	2.490	0.102	0.098
T	W0.35		W0.014	
DIA	Φ1.5 TYP.	deep0.2 TYP.	Φ0.059 TYP.	deep0.008 TYP.

TO263 PACKAGE INFORMATION

